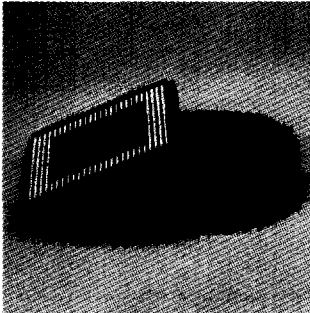
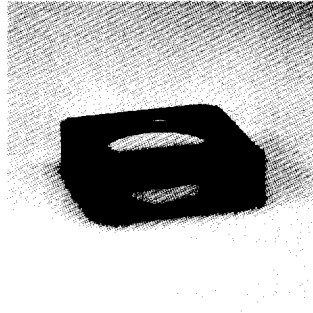


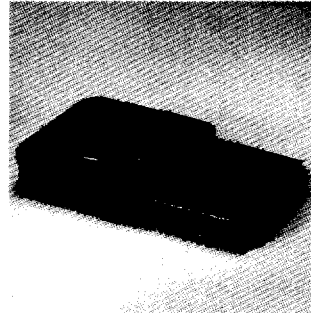
Pop-Top® BGA Adapter Socket Assembly with Heat Sink or Coin Screw



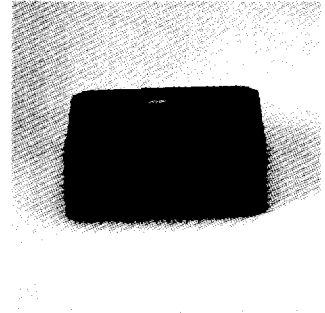
Adapter Socket Assembly with Heat Sink



Heat Sink Clip



Slide Clip Over Adapter Socket Assembly

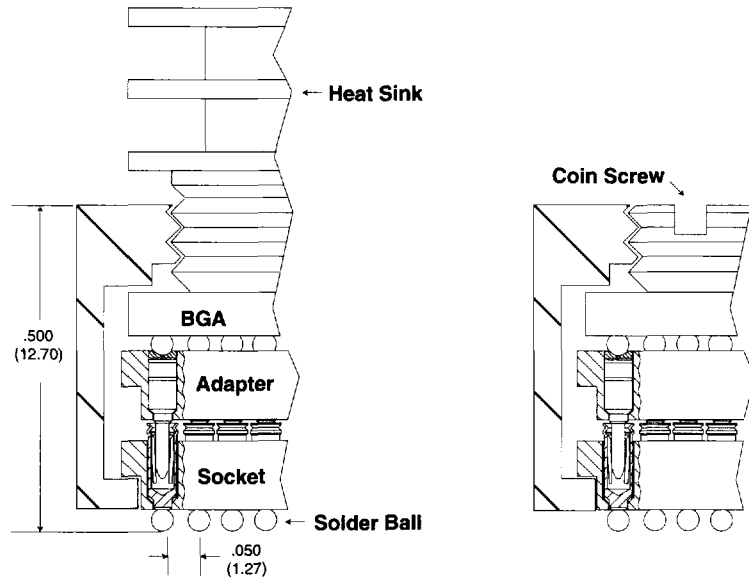


Complete Assembly After Screw Down of Coin Screw or Heat Sink

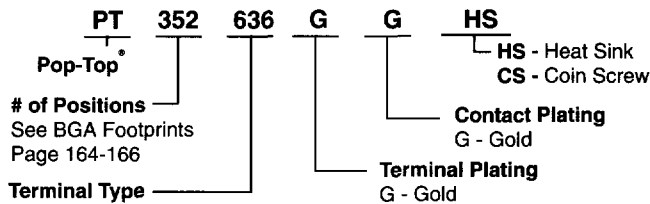
Features:

- Allows easy insertion and extraction of large BGAs.
- Allows effective connection of heat sink to device.
- See Ball Grid Array Soldering System pages 155 - 156 for specifications.
- Available in all footprints shown on pages 164 - 166.
- Limited stroke of adapter during insertion into socket allows lower extraction force.
- BGA device soldered to adapter.
- Lower lip of clip may be used to separate adapter from socket.

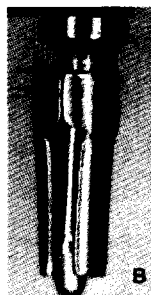
BGA Adapter Socket Assembly with Heat Sink or Coin Screw



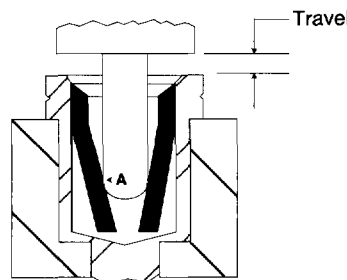
How To Order



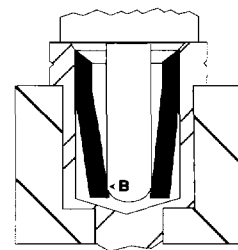
Includes entire assembly; clip, heat sink (or coin screw), adapter and socket.



Pop-Top® Action



1. "Zero" Insertion to point A



2. After travel & lock down with screw or heat sink to point B